CLAIM AMENDMENTS

1-16 (cancelled)

17. (original) A method of fabricating a support structure comprising: attaching a layer of material onto a substrate surface, said layer of material adaptable as said support structure;

forming said layer of material into said support structure;

treating said layer of material; and

etching said layer of material, such that said support structure is implementable during assembly of a display device.

18. (original) The method as recited in Claim 17 wherein said layer of material is photochemically sensitive glass and wherein said substrate surface is glass, and wherein the physical properties of said layer of material are compatible with the physical properties of said substrate surface.

19. (original) The method as recited in Claim 17 wherein said layer of material is photochemically insensitive glass and wherein said substrate surface is glass, and wherein the physical properties of said layer of material are compatible with the physical properties of said substrate surface.

CDST-C169.CIP Examiner: Nguyen, T. Serial No.: 09/993,740 Group Art Unit: 3644 20. (original)The method as recited in Claim 17 wherein attaching said layer of material onto said substrate surface further comprises performing a diffusion bonding process thereon.

21. (original) The method as recited in Claim 17 wherein attaching said layer of material onto said substrate surface further comprises performing a thin film sealing glass process thereon.

22. (original) The method as recited in Claim 17 further comprises blackening a surface of said layer of material, such that said blackened surface of said layer of material is interposed between said layer of material and said substrate surface when said layer of material is disposed upon said substrate.

23. (original) The method as recited in Claim 17 further comprises blackening a surface of said substrate surface, such that said blackened surface of said substrate surface is interposed between said layer of material and said substrate surface when said layer of material is disposed upon said substrate surface.

CDST-C169.CIP Examiner: Nguyen, T. Serial No.: 09/993,740 Group Art Unit: 3644 24. (original) The method as recited in Claim 17 wherein forming said

layer of material further comprises performing a photolithographic process

thereon.

25. (original) The method as recited in Claim 17 wherein treating said

layer of material further comprises applying an elevated temperature to said

layer of material and said substrate structure.

26. (original) The method as recited in Claim 17 wherein etching further

comprises sandblasting said layer of material with frozen particles of carbon

dioxide, such that said substrate surface to which said layer of material is

attached is unaffected by said sandblasting, when said layer of material is

photochemically insensitive glass.

27. (original) The method as recited in Claim 17 wherein etching said

layer of material further comprises chemically washing said layer of material,

such that said substrate surface is unaffected by said chemical washing when

said layer of material is attached to said substrate surface prior to said

washing, when said layer of material is photochemically sensitive glass.

CDST-C169.CIP

Serial No.: 09/993,740 Group Art Unit: 3644 5 Examiner: Nguyen, T.

28. (original)The method as recited in Claim 17 wherein said substrate surface is an anode faceplate of said display device, and wherein said support structure is interposed between said anode faceplate and a cathode back plate of said display device.

29. (original) The method as recited in Claim 17 wherein said substrate surface is a cathode back plate of said display device, and wherein said support structure is interposed between said cathode back plate and an anode faceplate of said display device.

30. (original)The method as recited in Claim 17 wherein said display device is an field emission display.

31-57 (cancelled)

CDST-C169.CIP Examiner: Nguyen, T. Serial No.: 09/993,740 Group Art Unit: 3644 The Examiner is invited to contact Applicants' undersigned representative if the Examiner believes such action would expedite resolution of the present Application.

Respectfully submitted,

WAGNER, MURABITO & HAO LLP

Date: 10/28/03

John P. Wagner Jr. Reg. No. 35,398

Two North Market Street Third Floor San Jose, California 95113 (408) 938-9060